

# DATA SHEET

**74LVC16245A; 74LVC16245A**  
16-bit bus transceiver with direction  
pin; 5 V tolerant (3-state)

Product specification  
Supersedes data of 2002 Oct 30

2003 Jan 30

Philips  
Semiconductors



**PHILIPS**

## 16-bit bus transceiver with direction pin; 5 V tolerant (3-state)

**74LVC16245A;  
74LVCH16245A**

### FEATURES

- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 to 3.6 V
- CMOS low power consumption
- MULTIBYTE™ flow-through standard pin-out architecture
- Low inductance multiple power and ground pins for minimum noise and ground bounce
- Direct interface with TTL levels
- High-impedance when  $V_{CC} = 0$  V
- All data inputs have bushold (74LVCH16245A only)
- Complies with JEDEC standard no. 8-1A
- ESD protection:  
HBM EIA/JESD22-A114-A exceeds 2000 V  
MM EIA/JESD22-A115-A exceeds 200 V.

### DESCRIPTION

The 74LVC(H)16245A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families. Inputs can be driven from either 3.3 or 5 V devices. In 3-state operation, outputs can handle 5 Volt. These features allow the use of these devices as a mixed 3.3 and 5 V environment.

The 74LVC(H)16245A is a 16-bit transceiver featuring non-inverting 3-state bus compatible outputs in both send and receive directions. The device features two output enable ( $n\overline{OE}$ ) inputs for easy cascading and two send/receive ( $nDIR$ ) inputs for direction control.  $n\overline{OE}$  controls the outputs so that the buses are effectively isolated. This device can be used as two 8-bit transceivers or one 16-bit transceiver.

The 74LVCH16245A bushold data inputs eliminates the need for external pull-up resistors to hold unused inputs.

### QUICK REFERENCE DATA

$GND = 0$  V;  $T_{amb} = 25$  °C;  $t_r = t_f \leq 2.5$  ns.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
$t_{PHL}/t_{PLH}$	propagation delay $nA_n$ to $nB_n$ ; $nB_n$ to $nA_n$	$C_L = 50$ pF; $V_{CC} = 3.3$ V	3.0	ns
$C_I$	input capacitance		5.0	pF
$C_{I/O}$	input/output capacitance		10	pF
$C_{PD}$	power dissipation capacitance per gate	$V_I = GND$ to $V_{CC}$ ; note 1	30	pF

### Note

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in Volts;

$N$  = total switching outputs;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

16-bit bus transceiver with direction pin; 5 V tolerant  
(3-state)

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#### ORDERING INFORMATION

TYPE NUMBER	PACKAGE				
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74LVC16245ADL	–40 to +85 °C	48	SSOP48	plastic	SOT370-1
74LVCH16245ADL	–40 to +85 °C	48	SSOP48	plastic	SOT370-1
74LVC16245ADGG	–40 to +85 °C	48	TSSOP48	plastic	SOT362-1
74LVCH16245ADGG	–40 to +85 °C	48	TSSOP48	plastic	SOT362-1
74LVC16245AEV	–40 to +85 °C	56	VFBGA56	plastic	SOT702-1
74LVCH16245AEV	–40 to +85 °C	56	VFBGA56	plastic	SOT702-1

#### FUNCTION TABLE

See note 1.

INPUT		OUTPUT	
$n\bar{OE}$	$nDIR$	$nA_n$	$nB_n$
L	L	$A = B$	inputs
L	H	inputs	$B = A$
H	X	Z	Z

#### Note

1. H = HIGH voltage level;  
L = LOW voltage level;  
X = don't care;  
Z = high-impedance OFF-state.

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### PINNING

SYMBOL	PINS	BALLS	DESCRIPTION
1DIR	1	A1	direction control input
1B <sub>0</sub>	2	B2	data inputs/output
1B <sub>1</sub>	3	B1	data inputs/output
GND	4, 10, 15, 21, 28, 34, 39, 45	B3, B4, D3, D4, G3, G4, J3, J4	ground (0 V)
1B <sub>2</sub>	5	C2	data inputs/output
1B <sub>3</sub>	6	C1	data inputs/output
V <sub>CC1</sub>	7, 18	C3, H3	supply voltage
1B <sub>4</sub>	8	D2	data inputs/output
1B <sub>5</sub>	9	D1	data inputs/output
1B <sub>6</sub>	11	E2	data inputs/output
1B <sub>7</sub>	12	E1	data inputs/output
2B <sub>0</sub>	13	F1	data output
2B <sub>1</sub>	14	F2	data output
2B <sub>2</sub>	16	G1	data output
2B <sub>3</sub>	17	G2	data output
2B <sub>4</sub>	19	H1	data output
2B <sub>5</sub>	20	H2	data output
2B <sub>6</sub>	22	J1	data output
2B <sub>7</sub>	23	J2	data output
2DIR	24	K1	direction control input
2OE	25	K6	output enable input (active LOW)
2A <sub>7</sub>	26	J5	data inputs/output
2A <sub>6</sub>	27	J6	data inputs/output
2A <sub>5</sub>	29	H5	data inputs/output
2A <sub>4</sub>	30	H6	data inputs/output
V <sub>CC2</sub>	31, 42	H4, C4	supply voltage
2A <sub>3</sub>	32	G5	data inputs/output
2A <sub>2</sub>	33	G6	data inputs/output
2A <sub>1</sub>	35	F5	data inputs/output
2A <sub>0</sub>	36	F6	data inputs/output
1A <sub>7</sub>	37	E6	data inputs/output
1A <sub>6</sub>	38	E5	data inputs/output
1A <sub>5</sub>	40	D6	data inputs/output
1A <sub>4</sub>	41	D5	data inputs/output
1A <sub>3</sub>	43	C6	data inputs/output
1A <sub>2</sub>	44	C5	data inputs/output
1A <sub>1</sub>	46	B6	data inputs/output
1A <sub>0</sub>	47	B5	data inputs/output
1OE	48	A6	output enable input (active LOW)

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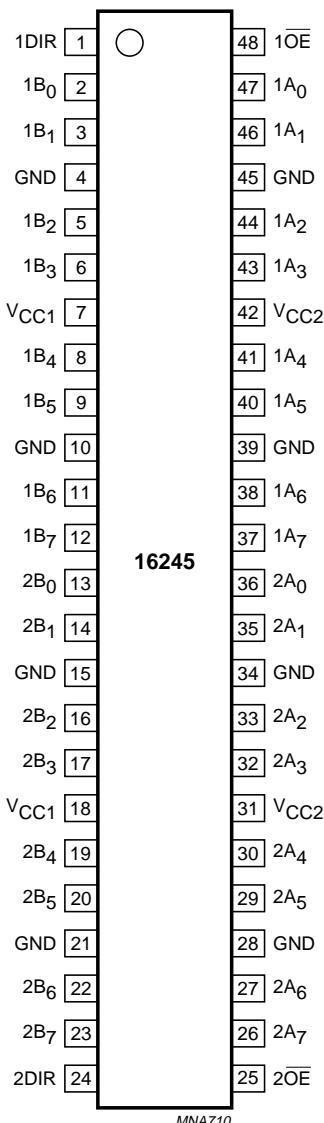


Fig.1 Pin configuration SSOP48 and TSSOP48.

A	1DIR					1OE
B	1B <sub>1</sub>	1B <sub>0</sub>	GND	GND	1A <sub>0</sub>	1A <sub>1</sub>
C	1B <sub>3</sub>	1B <sub>2</sub>	V <sub>CC1</sub>	V <sub>CC2</sub>	1A <sub>2</sub>	1A <sub>3</sub>
D	1B <sub>5</sub>	1B <sub>4</sub>	GND	GND	1A <sub>4</sub>	1A <sub>5</sub>
E	1B <sub>7</sub>	1B <sub>6</sub>			1A <sub>6</sub>	1A <sub>7</sub>
F	2B <sub>0</sub>	2B <sub>1</sub>			2A <sub>1</sub>	2A <sub>0</sub>
G	2B <sub>2</sub>	2B <sub>3</sub>	GND	GND	2A <sub>3</sub>	2A <sub>2</sub>
H	2B <sub>4</sub>	2B <sub>5</sub>	V <sub>CC1</sub>	V <sub>CC2</sub>	2A <sub>5</sub>	2A <sub>4</sub>
J	2B <sub>6</sub>	2B <sub>7</sub>	GND	GND	2A <sub>7</sub>	2A <sub>6</sub>
K	2DIR					2OE

1 2 3 4 5 6  
MNA707

Fig.2 Pin configuration VFBGA56.

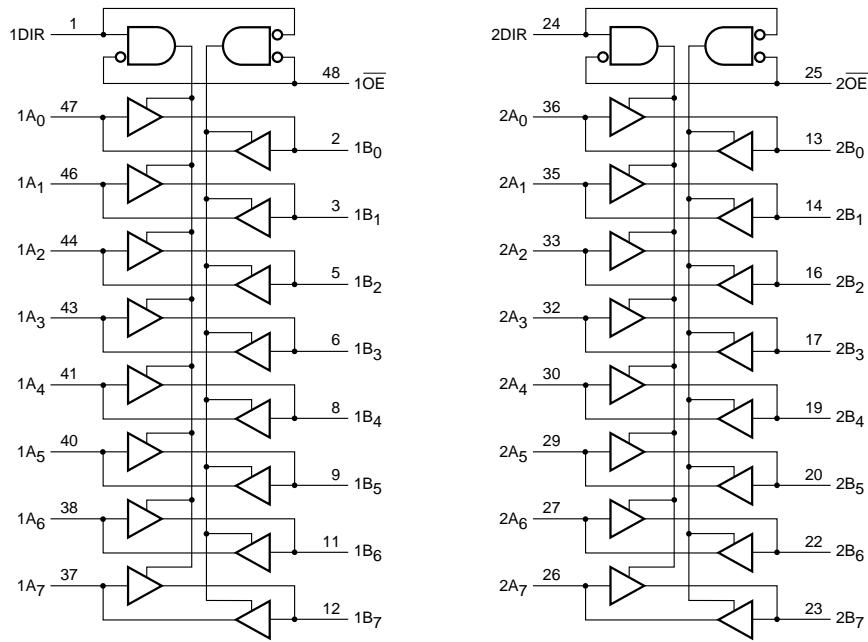
**16-bit bus transceiver with direction pin; 5 V tolerant  
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Fig.3 Logic symbol.

16-bit bus transceiver with direction pin; 5 V tolerant  
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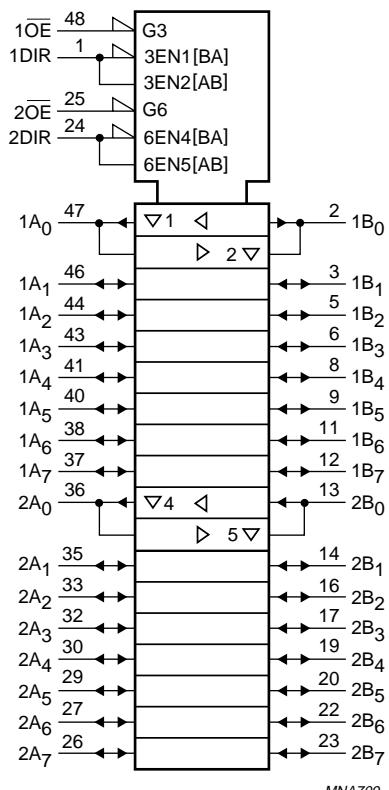


Fig.4 Logic symbol (IEEE/IEC).

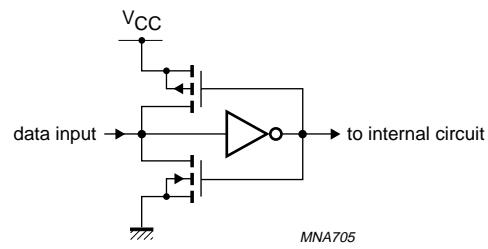


Fig.5 Bushold circuit.

16-bit bus transceiver with direction pin; 5 V tolerant  
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### RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage	for maximum speed performance	2.7	3.6	V
		for low voltage applications	1.2	3.6	V
$V_I$	input voltage		0	5.5	V
$V_O$	output voltage	output HIGH or LOW state	0	$V_{CC}$	V
		output 3-state	0	5.5	V
$T_{amb}$	operating ambient temperature	in free air	-40	+85	°C
$t_r, t_f$	input rise and fall times	$V_{CC} = 1.2$ to 2.7 V	0	20	ns/V
		$V_{CC} = 2.7$ to 3.6 V	0	10	ns/V

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input diode current	$V_I < 0$	-	-50	mA
$V_I$	input voltage	note 1	-0.5	+6.5	V
$I_{OK}$	output diode current	$V_O > V_{CC}$ or $V_O < 0$	-	±50	mA
$V_O$	output voltage	output HIGH or LOW state; note 1	-0.5	$V_{CC} + 0.5$	V
		output 3-state; note 1	-0.5	+6.5	V
$I_O$	output source or sink current	$V_O = 0$ to $V_{CC}$	-	±50	mA
$I_{CC}, I_{GND}$	$V_{CC}$ or GND current		-	±100	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	power dissipation SSOP and TSSOP package	temperature range from -40 to +85 °C; note 2	-	500	mW
	VFBGA package	temperature range from -40 to +85 °C; note 3	-	1000	mW

### Notes

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. Above 60 °C the value of  $P_D$  derates linearly with 5.5 mW/K.
3. Above 70 °C the value of  $P_D$  derates linearly with 1.8 mW/K.

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## DC CHARACTERISTICS

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		1.2	V <sub>CC</sub>	—	—	V
			2.7 to 3.6	2.0	—	—	V
V <sub>IL</sub>	LOW-level input voltage		1.2	—	—	GND	V
			2.7 to 3.6	—	—	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	2.7	V <sub>CC</sub> – 0.5	—	—	V
		I <sub>O</sub> = -12 mA	3.0	V <sub>CC</sub> – 0.2	V <sub>CC</sub>	—	V
		I <sub>O</sub> = -100 µA	3.0	V <sub>CC</sub> – 0.6	—	—	V
		I <sub>O</sub> = -18 mA	3.0	V <sub>CC</sub> – 0.8	—	—	V
		I <sub>O</sub> = -24 mA	3.0	—	—	—	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	2.7	—	—	0.40	V
		I <sub>O</sub> = 12 mA	3.0	—	—	0.20	V
		I <sub>O</sub> = 100 µA	3.0	—	—	0.55	V
		I <sub>O</sub> = 24 mA	3.0	—	—	—	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; note 2	3.6	—	±0.1	±5	µA
I <sub>OZ</sub>	3-state output OFF-state current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = 5.5 V or GND	3.6	—	0.1	±5	µA
I <sub>off</sub>	power off leakage supply	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0.0	—	0.1	±10	µA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	3.6	—	0.1	20	µA
ΔI <sub>CC</sub>	additional quiescent supply current per pin	V <sub>I</sub> = V <sub>CC</sub> – 0.6 V; I <sub>O</sub> = 0	2.7 to 3.6	—	5	500	µA
I <sub>BHL</sub>	bushold LOW sustaining current	V <sub>I</sub> = 0.8 V; notes 3, 4 and 5	3.0	75	—	—	µA
I <sub>BHH</sub>	bushold HIGH sustaining current	V <sub>I</sub> = 2.0 V; notes 3, 4 and 5	3.0	-75	—	—	µA
I <sub>BHLO</sub>	bushold LOW overdrive current	notes 3, 4 and 6	3.6	500	—	—	µA
I <sub>BHHO</sub>	bushold HIGH overdrive current	notes 3, 4 and 6	3.6	-500	—	—	µA

### Notes

1. All typical values are measured at V<sub>CC</sub> = 3.3 V and T<sub>amb</sub> = 25 °C.
2. For bushold parts, the bushold circuit is switched off when V<sub>I</sub> > V<sub>CC</sub> allowing 5.5 V on the input terminal.
3. Valid for data inputs of bushold parts (74LVCH16245A) only.
4. For data inputs only, control inputs do not have a bushold circuit.
5. The specified sustaining current at the data input holds the input below the specified V<sub>I</sub> level.
6. The specified overdrive current at the data input forces the data input to the opposite input state.

16-bit bus transceiver with direction pin; 5 V tolerant  
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### AC CHARACTERISTICS

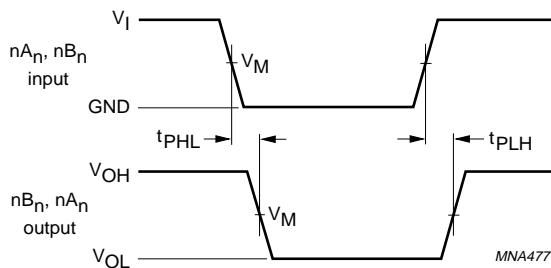
GND = 0 V;  $t_r = t_f \leq 2.5$  ns.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	$V_{CC}$ (V)				
$T_{amb} = -40$ to $+85$ °C							
$t_{PHL}/t_{PLH}$	propagation delay $nA_n$ to $nB_n$ ; $nB_n$ to $nA_n$	see Figs 6 and 8	1.2	—	13.0	—	ns
			2.7	1.5	—	5.5	ns
			3.0 to 3.6	1.5	3.0 <sup>(1)</sup>	4.5	ns
$t_{PZH}/t_{PZL}$	3-state output enable time $n\bar{OE}$ to $nA_n$ ; $n\bar{OE}$ to $nB_n$	see Figs 7 and 8	1.2	—	15.0	—	ns
			2.7	1.5	—	7.1	ns
			3.0 to 3.6	1.5	4.0 <sup>(1)</sup>	6.1	ns
$t_{PHZ}/t_{PLZ}$	3-state output disable time $n\bar{OE}$ to $nA_n$ ; $n\bar{OE}$ to $nB_n$	see Figs 7 and 8	1.2	—	11.0	—	ns
			2.7	1.5	—	6.6	ns
			3.0 to 3.6	1.5	4.0 <sup>(1)</sup>	5.6	ns

### Note

1. Typical values are measured at  $V_{CC} = 3.3$  V and  $T_{amb} = 25$  °C.

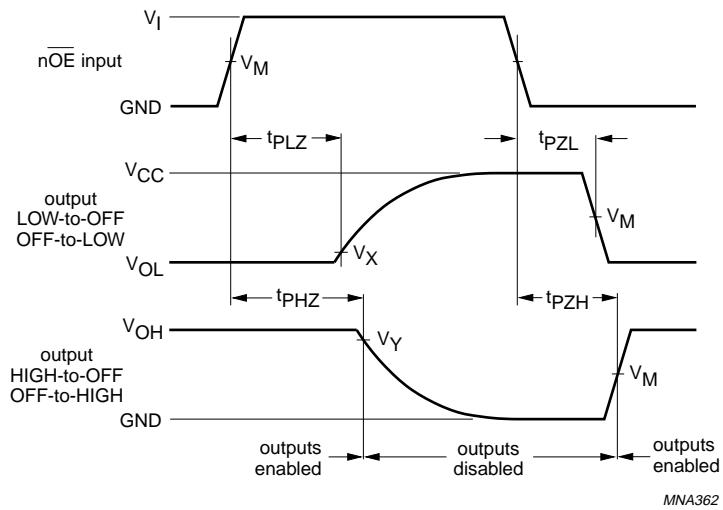
### AC WAVEFORMS



$V_{CC}$	$V_M$	INPUT	
		$V_I$	$t_r = t_f$
1.2 V	$0.5 \times V_{CC}$	$V_{CC}$	$\leq 2.5$ ns
2.7 V	1.5 V	2.7 V	$\leq 2.5$ ns
3.0 to 3.6 V	1.5 V	2.7 V	$\leq 2.5$ ns

$V_{OL}$  and  $V_{OH}$  are typical output voltage drop that occur with the output load.

Fig.6 The input ( $nA_n$ ,  $nB_n$ ) to output ( $nB_n$ ,  $nA_n$ ) propagation delays.

16-bit bus transceiver with direction pin; 5 V tolerant  
(3-state)74LVC16245A;  
74LVCH16245A

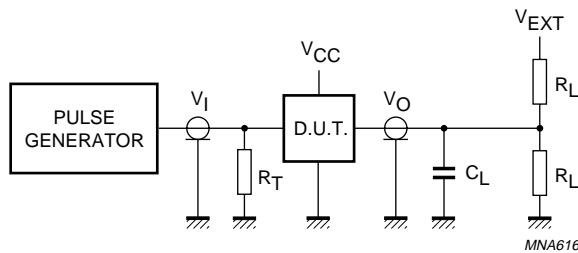
MNA362

V <sub>CC</sub>	V <sub>M</sub>	INPUT	
		V <sub>I</sub>	t <sub>r</sub> = t <sub>f</sub>
1.2 V	0.5 × V <sub>CC</sub>	V <sub>CC</sub>	≤ 2.5 ns
2.7 V	1.5 V	2.7 V	≤ 2.5 ns
3.0 to 3.6 V	1.5 V	2.7 V	≤ 2.5 ns

$$\begin{aligned}
 V_X &= V_{OL} + 0.3 \text{ V at } V_{CC} \geq 2.7 \text{ V;} \\
 V_X &= V_{OL} + 0.1 \text{ V at } V_{CC} < 2.7 \text{ V;} \\
 V_Y &= V_{OH} - 0.3 \text{ V at } V_{CC} \geq 2.7 \text{ V;} \\
 V_Y &= V_{OH} - 0.1 \text{ V at } V_{CC} < 2.7 \text{ V.}
 \end{aligned}$$

V<sub>OL</sub> and V<sub>OH</sub> are typical output voltage drop that occur with the output load.

Fig.7 3-state enable and disable times.

16-bit bus transceiver with direction pin; 5 V tolerant  
(3-state)74LVC16245A;  
74LVCH16245A

$V_{CC}$	$V_I$	$C_L$	$R_L$	$V_{EXT}$		
				$t_{PLH}/t_{PHL}$	$t_{PZH}/t_{PHZ}$	$t_{PZL}/t_{PLZ}$
1.2 V	$V_{CC}$	50 pF	500 $\Omega$	open	GND	$2 \times V_{CC}$
2.7 V	2.7 V	50 pF	500 $\Omega$	open	GND	$2 \times V_{CC}$
3.0 to 3.6 V	2.7 V	50 pF	500 $\Omega$	open	GND	$2 \times V_{CC}$

Definitions for test circuits:

 $R_L$  = Load resistor. $C_L$  = Load capacitance including jig and probe capacitance. $R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

Fig.8 Load circuitry for switching times.

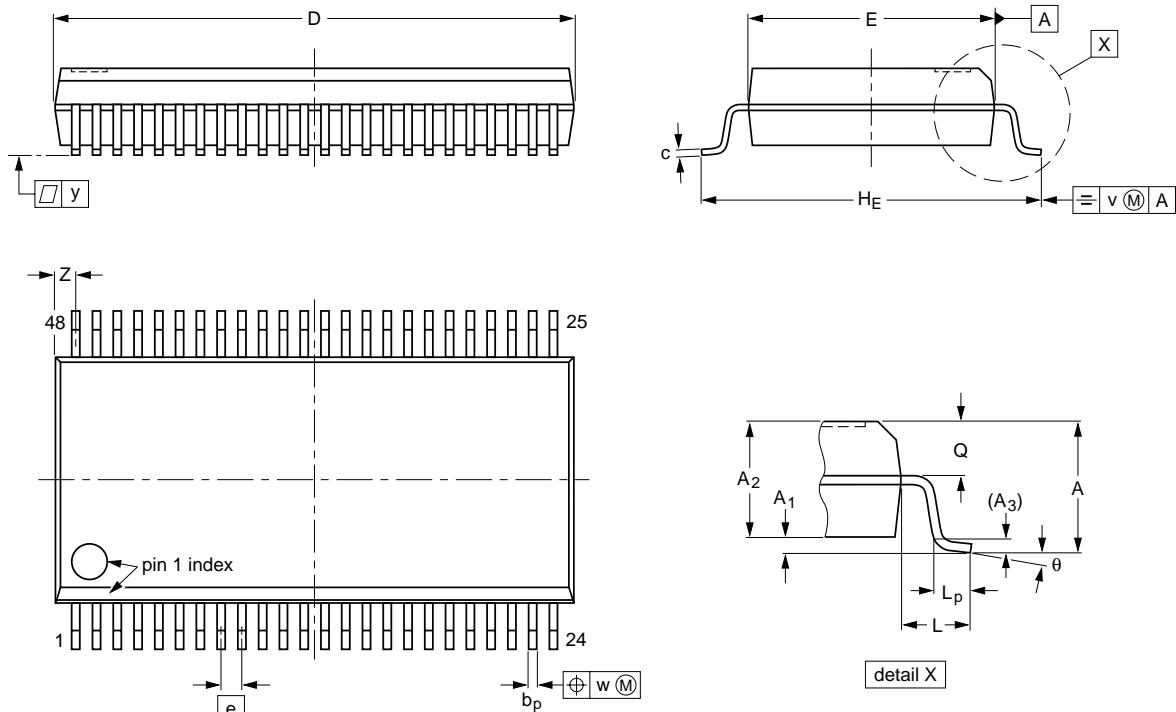
16-bit bus transceiver with direction pin; 5 V tolerant  
(3-state)

74LVC16245A;  
74LVCH16245A

## PACKAGE OUTLINES

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

SOT370-1



### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.8 0.2	0.4 0.2	2.35 2.20	0.25	0.3 0.13	0.22 15.75	16.00 7.6	7.6 7.4	0.635 10.1	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25 0.25	0.18 0.18	0.1 0.1	0.85 0.40	8° 0°

### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

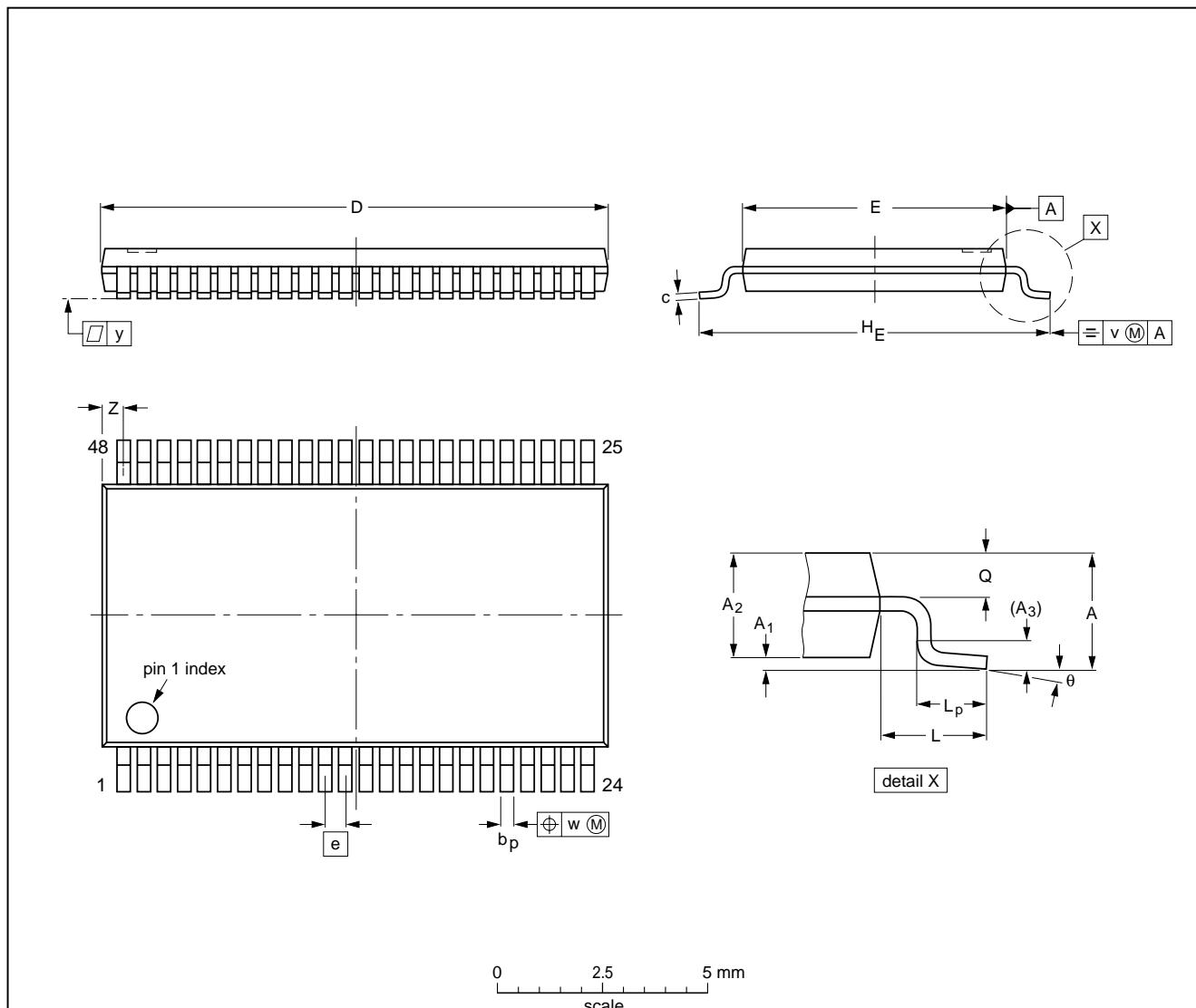
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT370-1		MO-118				95-02-04- 99-12-27

16-bit bus transceiver with direction pin; 5 V tolerant  
(3-state)

74LVC16245A;  
74LVCH16245A

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1



**DIMENSIONS (mm are the original dimensions).**

UNIT	A <sub>max.</sub>	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	12.6 12.4	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.8 0.4	8° 0°

**Notes**

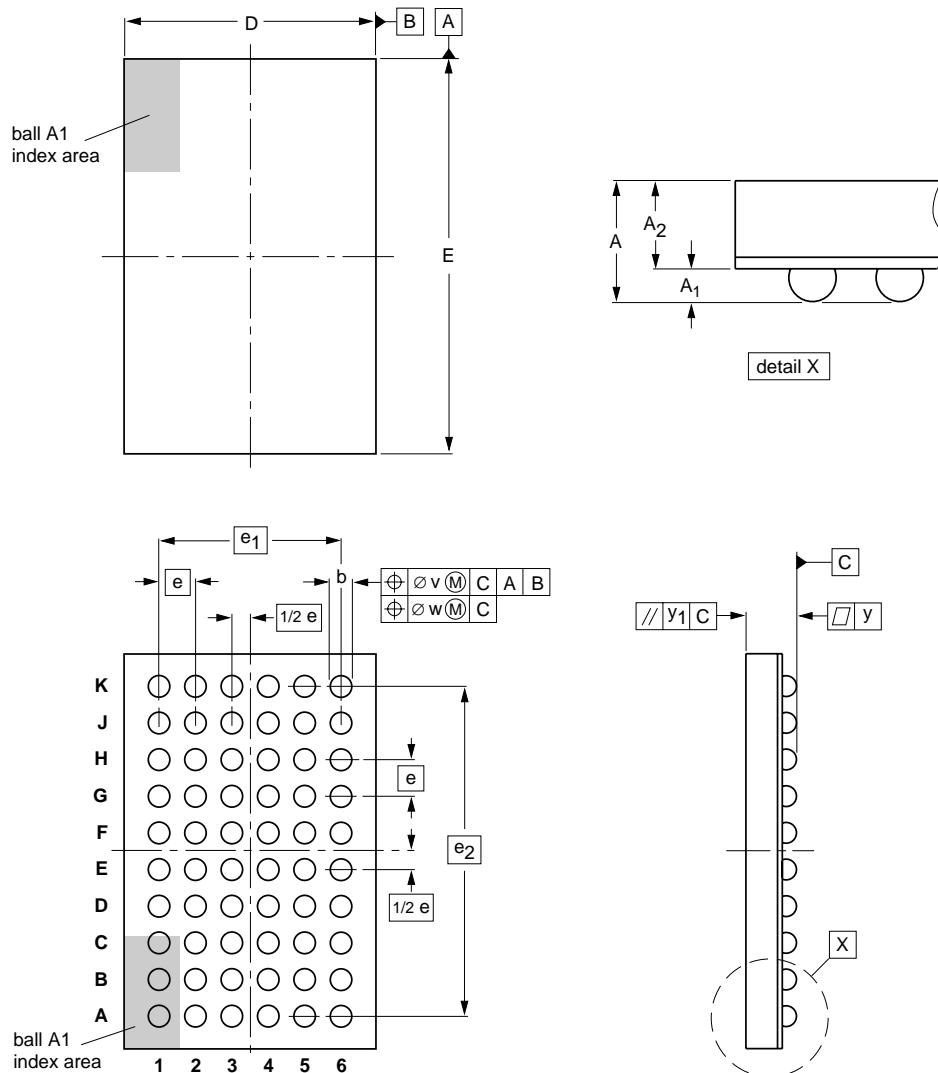
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT362-1		MO-153				-95-02-10 99-12-27

16-bit bus transceiver with direction pin; 5 V tolerant  
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74LVC16245A;  
74LVCH16245A

VFBGA56: plastic very thin fine-pitch ball grid array package; 56 balls; body 4.5 x 7 x 0.65 mm SOT702-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1	0.3 0.2	0.7 0.6	0.45 0.35	4.6 4.4	7.1 6.9	0.65	3.25	5.85	0.15	0.08	0.08	0.1

0 2.5 5 mm  
scale

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16-bit bus transceiver with direction pin; 5 V tolerant (3-state)	74LVC16245A; 74LVCH16245A
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## SOLDERING

### Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

### Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferable be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

### Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C. A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

### Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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**Suitability of surface mount IC packages for wave and reflow soldering methods**

PACKAGE <sup>(1)</sup>	SOLDERING METHOD	
	WAVE	REFLOW <sup>(2)</sup>
BGA, LBGA, LFBGA, SQFP, TFBGA, VFBGA DHVQFN, HBCC, HBGA, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable not suitable <sup>(3)</sup>	suitable suitable
PLCC <sup>(4)</sup> , SO, SOJ LQFP, QFP, TQFP	suitable not recommended <sup>(4)(5)</sup>	suitable suitable
SSOP, TSSOP, VSO, VSSOP	not recommended <sup>(6)</sup>	suitable

**Notes**

1. For more detailed information on the BGA packages refer to the “(LF)BGA Application Note” (AN01026); order a copy from your Philips Semiconductors sales office.
2. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the “Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods”.
3. These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
4. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
5. Wave soldering is suitable for LQFP, TQFP and QFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
6. Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

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**NOTES**

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